Exposure of the inner layers and transfer of the pattern

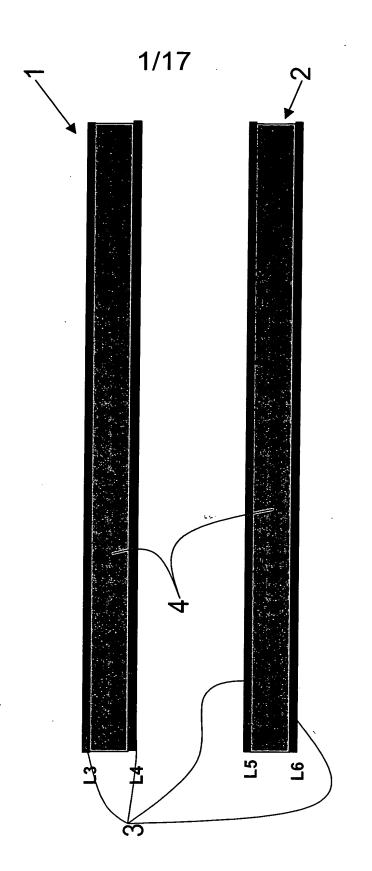
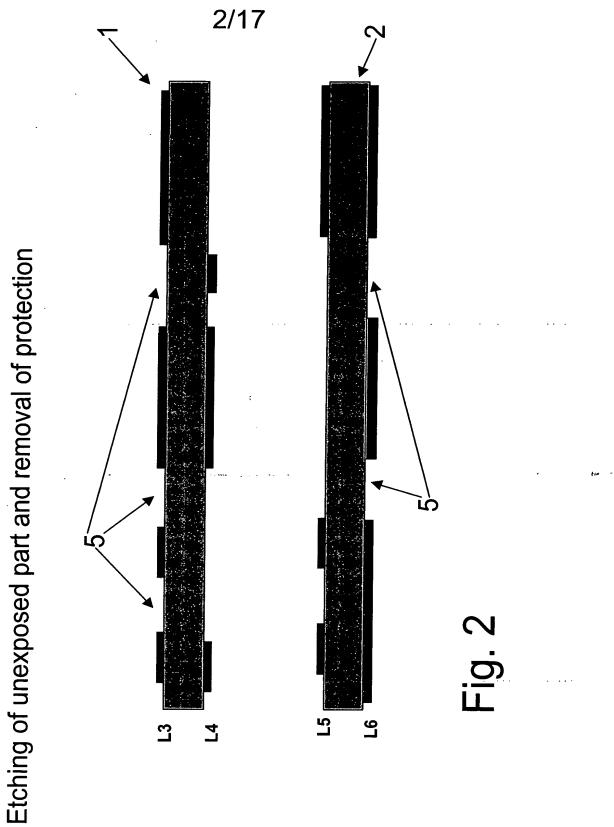
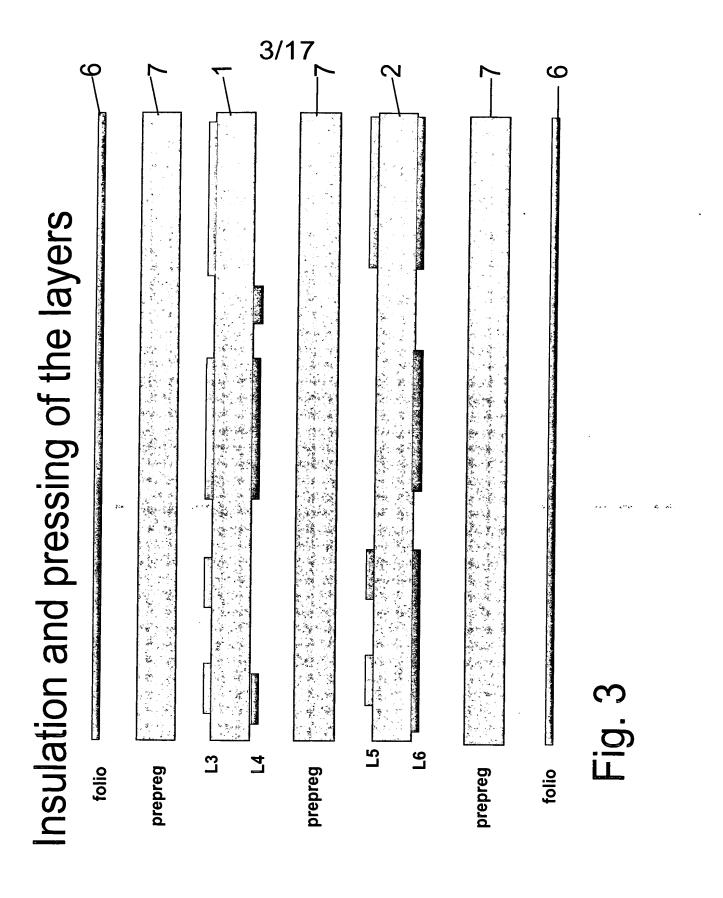
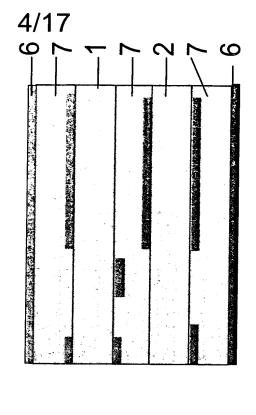


Fig. 1





Through-drilling of the inner layers



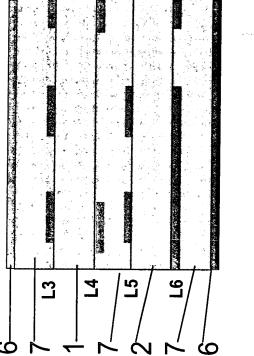


Fig. 4

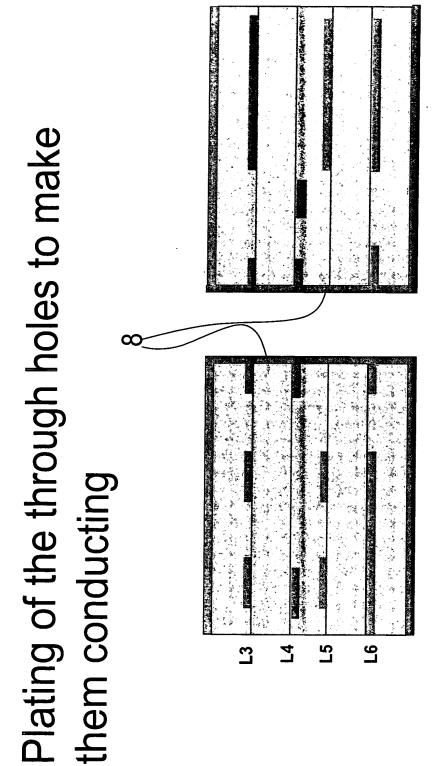
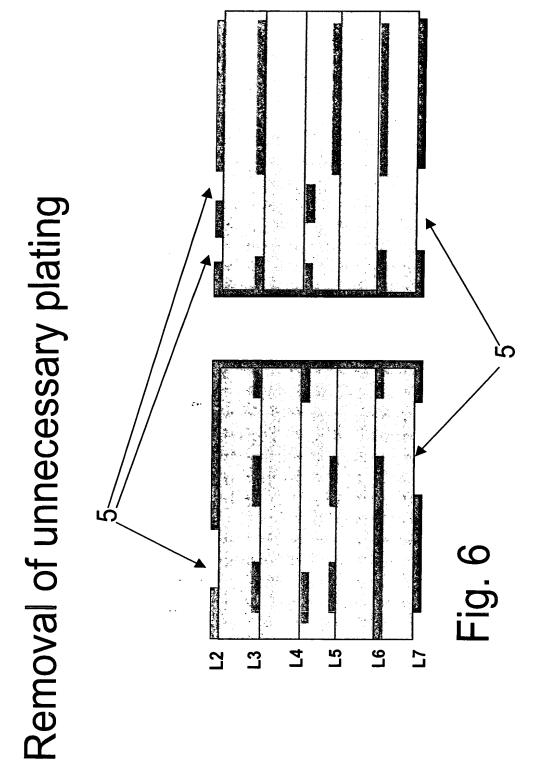


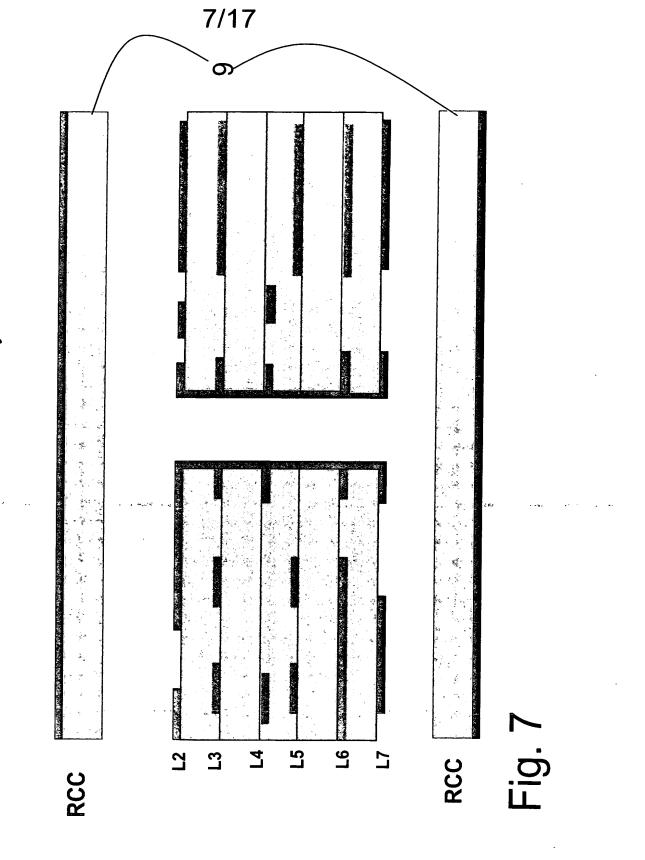
Fig. 5

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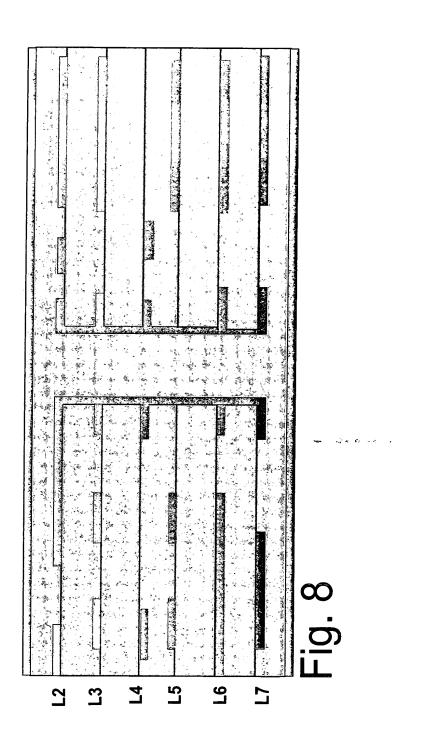


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Formation of the microvia layers, i.e. the outer layers

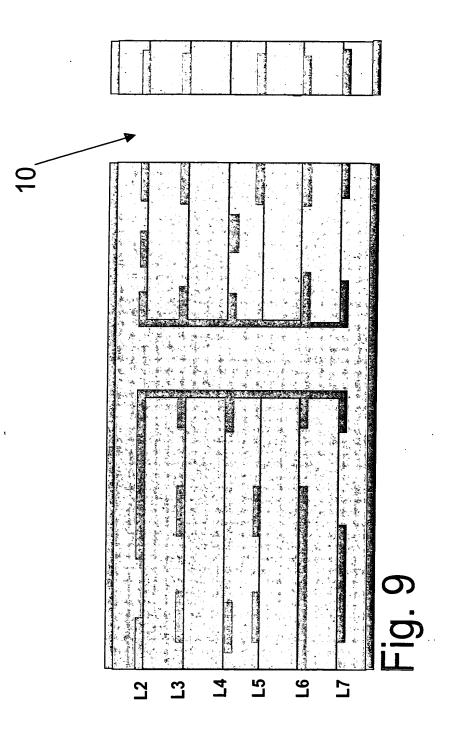


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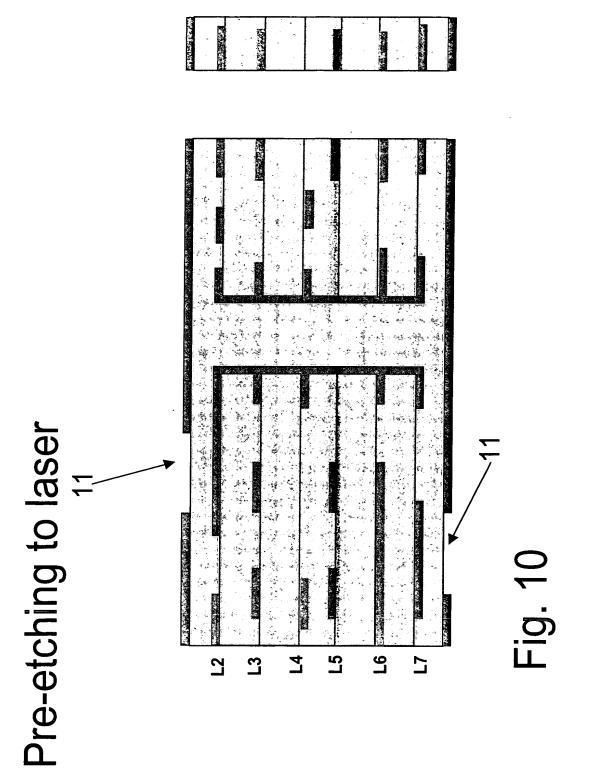
Pressing together



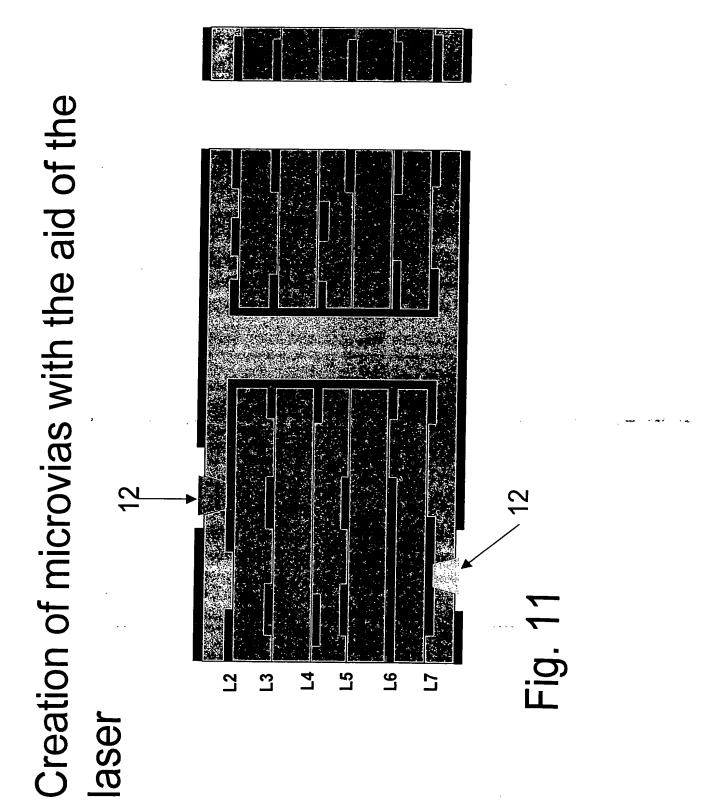


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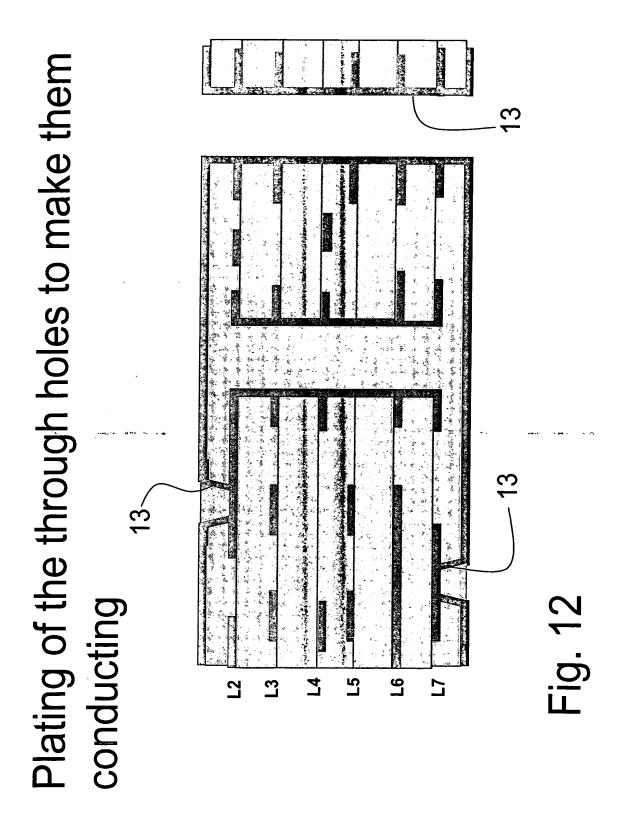


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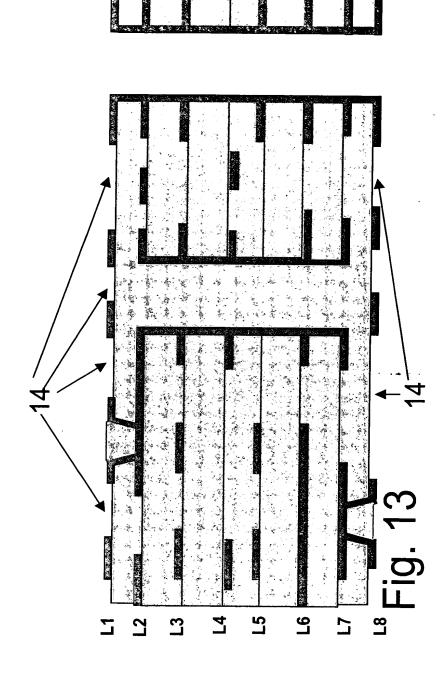


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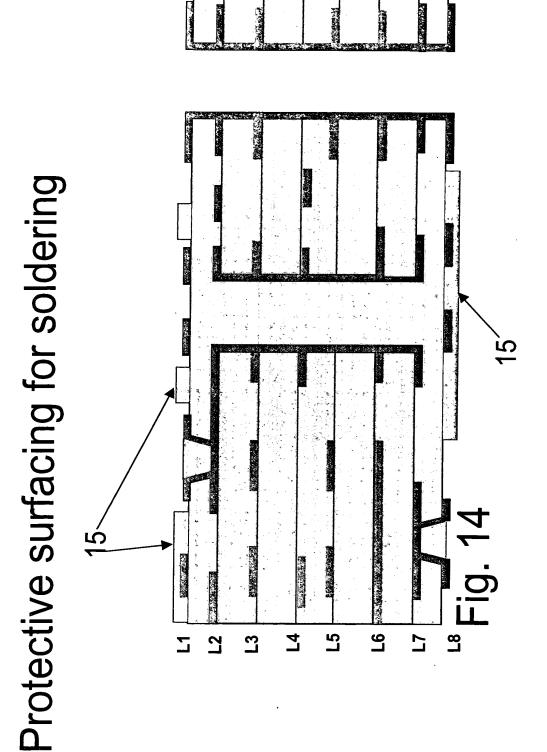


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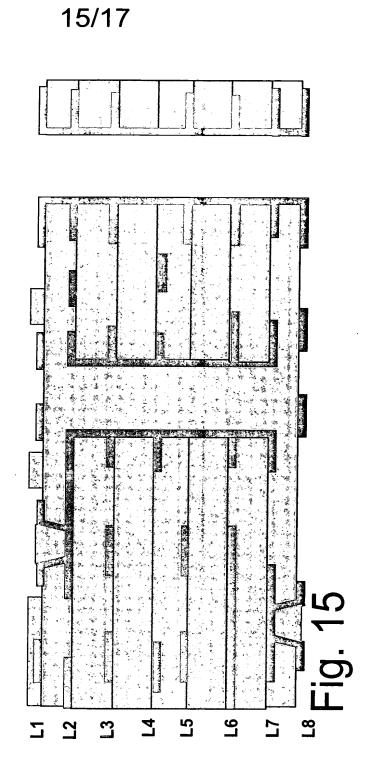
Formation of the conducting pattern

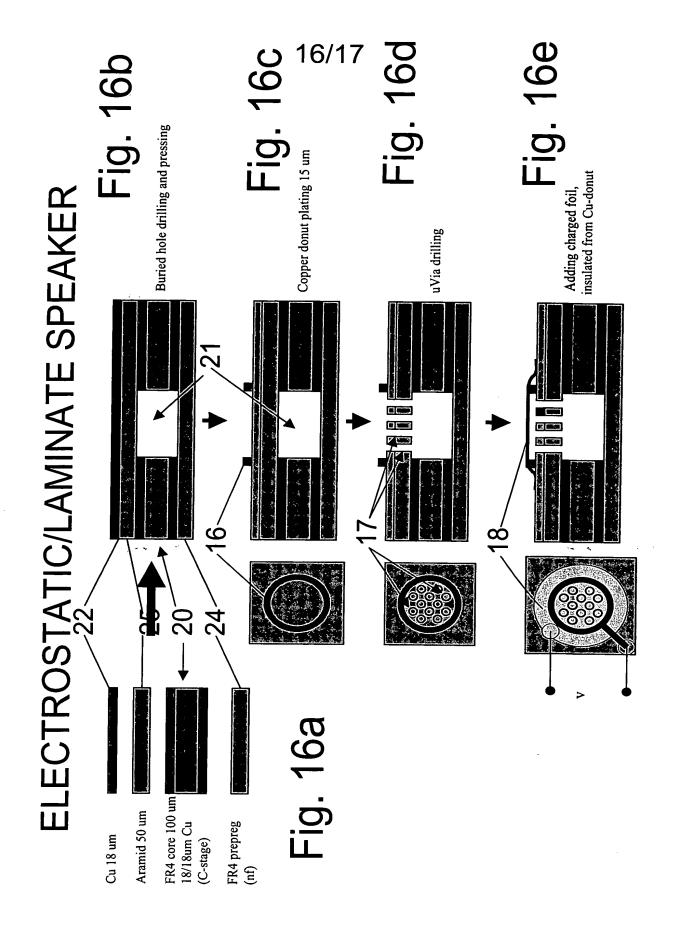
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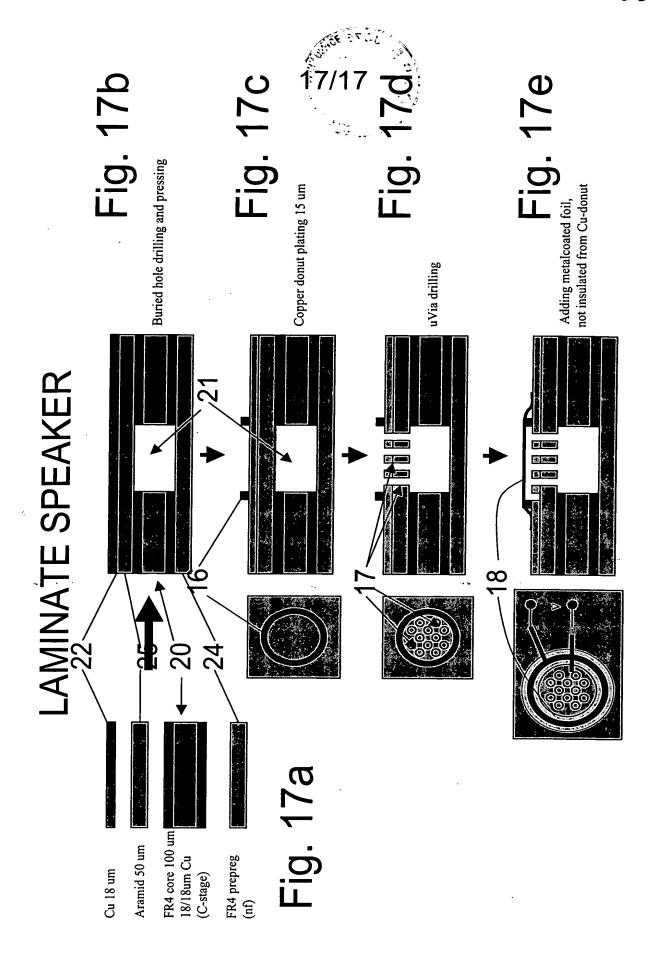


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8-layer microvia plate containing buried through holes







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